



Material Content Data Sheet



Sales Product Name		BG 3130 H6327		Issued		27. October 2015			
MA#		MA000793202							
Package		PG-SOT363-6-4		Weight*		6.27 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.005	0.08		816		
	non noble metal	tin	7440-31-5	0.001	0.02		210		
	inorganic material	silicon	7440-21-3	0.038	0.60	0.70	6045	7071	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92		
	non noble metal	titanium	7440-32-6	0.003	0.05		458		
	non noble metal	chromium	7440-47-3	0.009	0.14		1374		
	non noble metal	copper	7440-50-8	2.860	45.61	45.81	455995	457919	
wire	non noble metal	copper	7440-50-8	0.014	0.22	0.22	2215	2215	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4888		
	plastics	epoxy resin	-	0.659	10.51		105098		
	inorganic material	silicondioxide	60676-86-0	2.376	37.88	48.88	378842	488828	
leadfinish	non noble metal	tin	7440-31-5	0.216	3.44	3.44	34423	34423	
plating	noble metal	silver	7440-22-4	0.060	0.95	0.95	9544	9544	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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